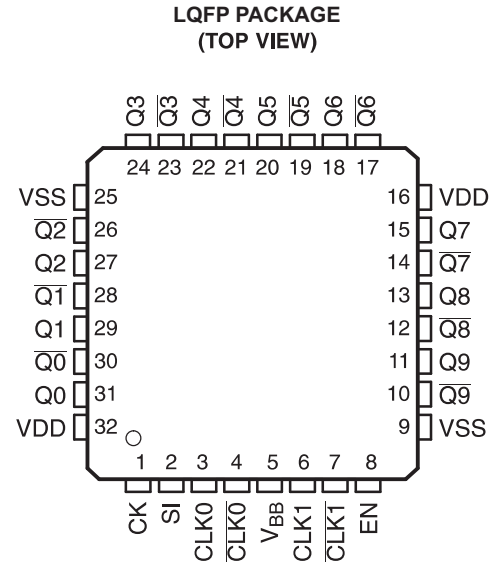


Not Recommended for New Designs
PROGRAMMABLE LOW-VOLTAGE 1:10 LVDS CLOCK DRIVER

FEATURES

- Low-Output Skew <30 ps (Typical) for Clock-Distribution Applications
- Distributes One Differential Clock Input to 10 LVDS Differential Clock Outputs
- V_{CC} range 2.5 V \pm 5%
- Typical Signaling Rate Capability of Up to 1.1 GHz
- Configurable Register (SI/CK) Individually Enables Disables Outputs, Selectable $\overline{CLK0}$, $\overline{CLK1}$ or $\overline{CLK1}$ Inputs
- Full Rail-to-Rail Common-Mode Input Range
- Receiver Input Threshold \pm 100 mV
- Available in 32-Pin LQFP Package
- Fail-Safe I/O-Pins for $V_{DD} = 0$ V (Power Down)



DESCRIPTION

The CDCLVD110 clock driver distributes one pair of differential LVDS clock inputs (either CLK0 or CLK1) to 10 pairs of differential clock outputs (Q0, Q9) with minimum skew for clock distribution. The CDCLVD110 is specifically designed for driving 50- Ω transmission lines.

When the control enable is high (EN = 1), the 10 differential outputs are programmable in that each output can be individually enabled/disabled (3-stated) according to the first 10 bits loaded into the shift register. Once the shift register is loaded, the last bit selects either CLK0 or CLK1 as the clock input. However, when EN = 0, the outputs are not programmable and all outputs are enabled.

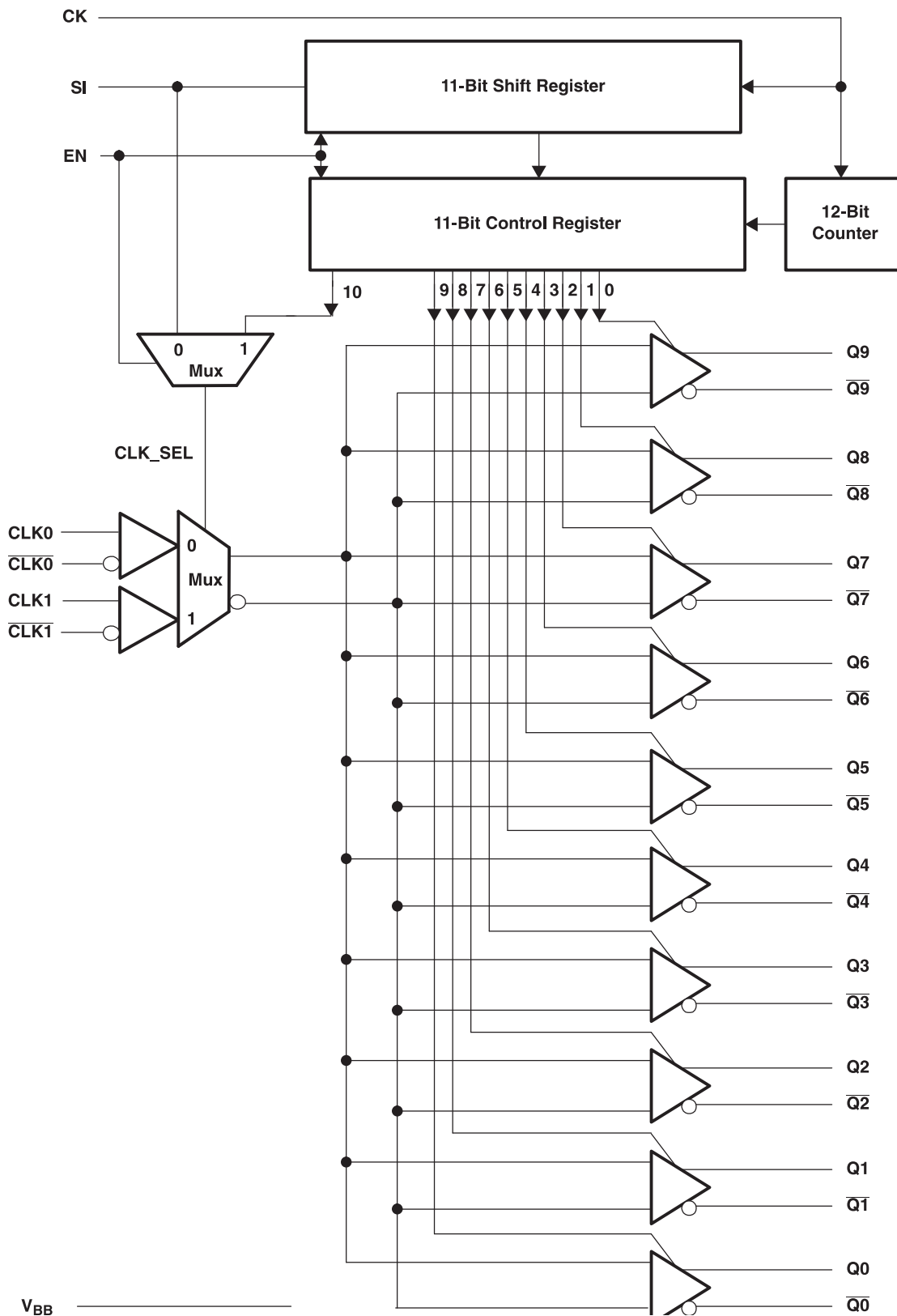
The CDCLVD110 is characterized for operation from -40°C to 85°C .

Not Recommended for New Designs. Use CDCLVD110A as a Replacement.



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FUNCTIONAL BLOCK DIAGRAM



TERMINAL FUNCTIONS

TERMINAL		I/O	DESCRIPTION
NAME	NO.		
CK	1	I	Control register input clock, features a 120-kΩ pullup resistor
SI	2	I	Control register serial input/CLK Select, features a 120-kΩ pulldown resistor
CLK0	3	I	True differential input, LVDS
$\overline{\text{CLK0}}$	4	I	Complementary differential input, LVDS
V _{BB}	5	O	Reference voltage output
CLK1	6	I	True differential input, LVDS
$\overline{\text{CLK1}}$	7	I	Complementary differential input, LVDS
EN	8	I	Control enable (for programmability), features a 120-kΩ pulldown resistor, input
V _{SS}	9, 25		Device ground
V _{DD}	16, 32		Supply voltage
Q [9:0]	11, 13, 15, 18, 20, 22, 24, 27, 29, 31	O	Clock outputs, these outputs provide low-skew copies of CLKIN
$\overline{\text{Q}}[9:0]$	10, 12, 14, 17, 19, 21, 23, 26, 28, 30	O	Complementary clock outputs, these outputs provide low-skew copies of CLKIN

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

	VALUE	UNIT
V _{DD} Supply voltage	–0.3 to 2.8	V
V _I Input voltage	–0.2 to (V _{DD} + 0.2)	V
V _O V _I Output voltage	–0.2 to (V _{DD} + 0.2)	V
Q _n , $\overline{\text{Q}}_n$, I _{OSD} Driver short circuit current	Continuous	
Electrostatic discharge (HBM 1.5 kΩ, 100 pF), ESD	>2000	V

(1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

	MIN	NOM	MAX	UNIT
V _{DD} Supply voltage	2.375	2.5	2.625	V
V _{IC} Receiver common-mode input voltage	0.5 V _{ID}		V _{DD} – 0.5 V _{ID}	V
T _A Operating free-air temperature	–40		85	°C

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
DRIVER					
V _{OD} Differential output voltage	R _L = 100Ω	250	450	600	mV
ΔV _{OD} V _{OD} magnitude change				50	mV
V _{OS} Offset voltage	–40°C to 85°C	0.95	1.2	1.45	V
ΔV _{OS} V _{OS} magnitude change				350	mV
I _{OS} Output short circuit current	V _O = 0 V V _{OD} = 0 V			–20 20	mA
V _{BB} Reference output voltage	V _{DD} = 2.5 V, I _{BB} = –100 μA	1.15	1.25	1.35	V
C _O Output capacitance	V _O = V _{DD} or GND		3		pF

ELECTRICAL CHARACTERISTICS (continued)

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
RECEIVER						
V _{IDH}	Input threshold high				100	mV
V _{IDL}	Input threshold low		-100			mV
V _{ID}	Input differential voltage		200			mV
I _{IH}	Input current, CLK0/ $\overline{\text{CLK0}}$, CLK1/ $\overline{\text{CLK1}}$	V _I = V _{DD}	-5		5	μA
I _{IL}		V _I = 0 V				
C _I	Input capacitance	V _I = V _{DD} or GND		3		pF
SUPPLY CURRENT						
I _{DD}	Supply current	Full loaded	All outputs enabled and loaded, R _L = 100 Ω, f = 0 Hz		130	mA
		No load	Outputs enabled, no output load, f = 0 Hz		35	
I _{DDZ}	3-State	All outputs 3-state by control logic, f = 0 Hz		35		

JITTER CHARACTERISTICScharacterized with CDCLVD110 performance EVM, V_{DD} = 3.3 V, OUTPUTS NOT UNDER TEST are terminated to 50Ω

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{jitterLVDS}	Additive phase jitter from input to LVDS output Q3 and $\overline{\text{Q3}}$	12 kHz to 5 MHz, f _{out} = 30.72 MHz		650		fs rms
		12 kHz to 20 MHz, f _{out} = 125 MHz		299		

LVDS — SWITCHING CHARACTERISTICSover recommended operating free-air temperature range, V_{DD} = 2.5 V ±5%

PARAMETER		FROM (INPUT)	TO (OUTPUT)	MIN	TYP	MAX	UNIT
t _{PLH}	Propagation delay low-to-high	CLK0, $\overline{\text{CLK0}}$ CLK1, $\overline{\text{CLK1}}$	Qn, $\overline{\text{Qn}}$		2	3	ns
t _{PHL}	Propagation delay high-to-low	CLK0, $\overline{\text{CLK0}}$ CLK1, $\overline{\text{CLK1}}$	Qn, $\overline{\text{Qn}}$		2	3	ns
t _{duty}	Duty cycle	CLK0, $\overline{\text{CLK0}}$ CLK1, $\overline{\text{CLK1}}$	Qn, $\overline{\text{Qn}}$	45%		55%	
t _{sk(o)}	Output skew		Any Qn, $\overline{\text{Qn}}$		30		ps
t _{sk(p)}	Pulse skew		Any Qn, $\overline{\text{Qn}}$			50	ps
t _{sk(pp)}	Part-to-part skew		Any Qn, $\overline{\text{Qn}}$			600	ps
t _r	Output rise time, 20% to 80%, R _L = 100 Ω, C _L = 5 pF		Any Qn, $\overline{\text{Qn}}$			350	ps
t _f	Output fall time, 20% to 80%, R _L = 100 Ω, C _L = 5 pF		Any Qn, $\overline{\text{Qn}}$			350	ps
f _{clk}	Max input frequency	CLK0, $\overline{\text{CLK0}}$ CLK1, $\overline{\text{CLK1}}$	Any Qn, $\overline{\text{Qn}}$	900	1100		MHz

CONTROL REGISTER CHARACTERISTICSover recommended operating free-air temperature range, V_{DD} = 2.5 V ±5% (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{MAX}	Maximum frequency of shift register		100	150		MHz
t _{su}	Setup time, clock to SI				2	ns
t _h	Hold time, clock to SI				1.5	ns
t _{removal}	Removal time, enable to clock				1.5	ns
t _w	Clock pulse width, minimum		3			ns
V _{IH}	Logic input high	V _{DD} = 2.5 V	2			V
V _{IL}	Logic input low	V _{DD} = 2.5 V			0.8	V

CONTROL REGISTER CHARACTERISTICS (continued)

over recommended operating free-air temperature range, $V_{DD} = 2.5\text{ V} \pm 5\%$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{IH}	Input current, CK pin	$V_I = V_{DD}$	-5		5	μA
	Input current, SI and EN pins		10		-30	
I_{IL}	Input current, CK pin	$V_I = \text{GND}$	-10		30	μA
	Input current, SI and EN pins		-5		5	

SPECIFICATION OF CONTROL REGISTER

The CDCLVD110 is provided with an 11-bit, serial-in shift register and an 11-bit control register. The control Register enables/disables each output clock and selects either CLK0 or CLK1 as the input clock. The CDCLVD110 has two modes of operation:

Programmable Mode (EN=1)

The shift register utilizes a serial input (SI) and a clock input (CK). Once the shift register is loaded with 11 clock pulses, the twelfth clock pulse loads the control register. The first bit (bit 0) on SI enables the Q9, $\overline{Q9}$ output pair, and the tenth bit (bit 9) enables the Q0, $\overline{Q0}$ pair. The eleventh bit (bit 10) on SI selects either CLK0 or CLK1 as the input clock; a bit value of 0 selects CLK0, whereas a bit value of 1 selects CLK1. To restart the control register configuration, a reset of the state machine must be done with a clock pulse on CK (shift register clock input) and EN set to low. The control register can be configured only once after each reset.

Standard Mode (EN=0)

In this mode, the CDCLVD110 is not programmable and all the clock outputs are enabled. The clock input (CLK0 or CLK1) is selected with the SI pin, as is shown in the table entitled control register.

STATE-MACHINE INPUTS			OUTPUT
EN	SI	CK	
L	L	X	All outputs enabled, CLK0 selected, control register disabled, default state
L	H	X	All outputs enabled, CLK1 selected, control register disabled
H	L	\uparrow	First stage stores L, other stage stores data of previous stage
H	H		First stage stores H, other stage stores data of previous stage
L	X		Reset of state machine, shift and control registers

CONTROL REGISTER		
BIT 10	BITS [0-9]	$Q_N[0-9]$
L	H	CLK0
H	H	CLK1
X	L	Outputs disabled

SERIAL INPUT (SI) SEQUENCE										
BIT 10	BIT 9	BIT 8	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
CLK_SEL	Q0	Q1	Q2	Q3	Q4	Q5	Q6	Q7	Q8	Q9

TRUTH TABLE FOR CONTROL LOGIC									
CK	EN	SI	CLK0	$\overline{\text{CLK0}}$	CLK1	$\overline{\text{CLK1}}$	Q(0-9)	$\overline{\text{Q(0-9)}}$	
L	L	L	L	H	X	X	L	H	
L	L	L	H	L	X	X	H	L	
L	L	L	Open	Open	X	X	L	H	
L	L	H	X	X	L	H	L	H	
L	L	H	X	X	H	L	H	L	
L	L	H	X	X	Open	Open	L	H	
All outputs enabled			X = Don't care						

APPLICATION INFORMATION

Fall-Safe Information

For $V_{DD} = 0$ V (power-down mode) the CDCLVD110 has fail-safe input and output pins. In power-on mode, fail-safe biasing at input pins can be accomplished with a 10-k Ω pullup resistor from CLK0/CLK1 to VDD and a 10-k Ω pulldown resistor from $\overline{\text{CLK0/CLK1}}$ to GND.

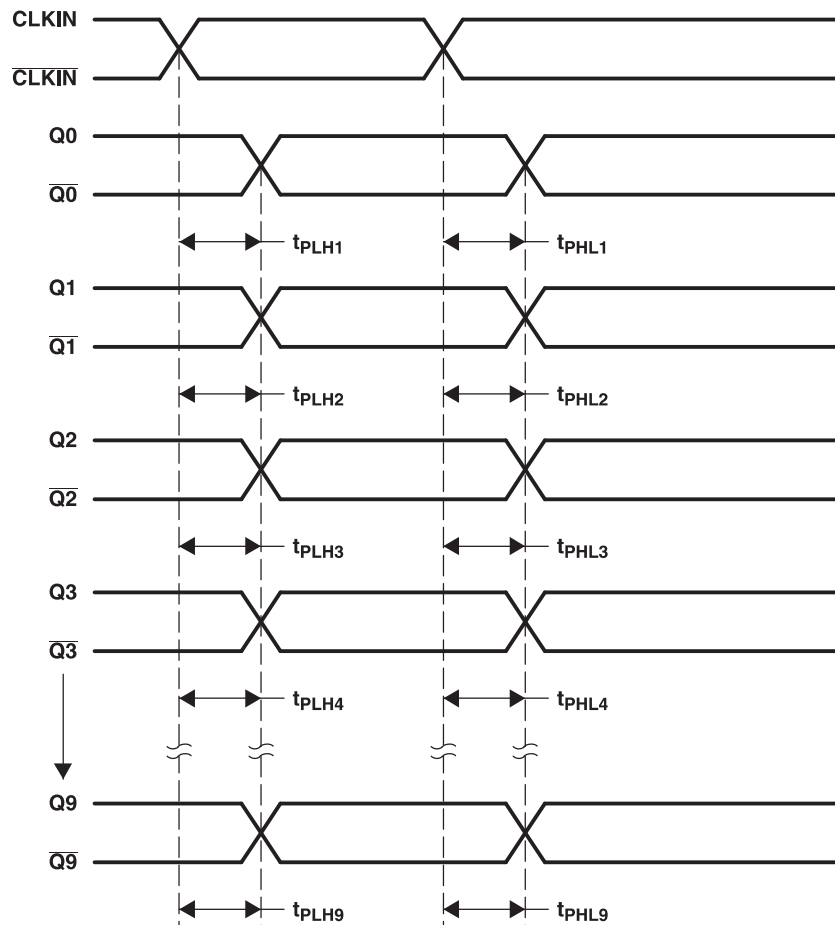
LVDS Receiver Input Termination

The LVDS receiver inputs need to have 100- Ω termination resistors placed as close as possible across the input pins.

Control Inputs Termination

No external termination is required. The CK control input has an internal 120-k Ω pullup resistor while SI- and EN-control inputs each have an internal 120-k Ω pulldown resistor. If the control pins are left open per the default, all outputs are enabled, CLK0, $\overline{\text{CLK0}}$ is selected, and the control register is disabled.

PARAMETER MEASUREMENT INFORMATION



- A. Output skew, $t_{sk(o)}$, is calculated as the greater of:
 - The difference between the fastest and the slowest t_{PLHn} ($n = 1, 2, \dots, 10$)
 - The difference between the fastest and the slowest t_{PHLn} ($n = 1, 2, \dots, 10$)
- B. Part-to-part skew, $t_{sk(pp)}$, is calculated as the greater of:
 - The difference between the fastest and the slowest t_{PLHn} ($n = 1, 2, \dots, 10$) across multiple devices
 - The difference between the fastest and the slowest t_{PHLn} ($n = 1, 2, \dots, 10$) across multiple devices
- C. Pulse skew, $t_{sk(p)}$, is calculated as the magnitude of the absolute time difference between the high-to-low (t_{PHL}) and the low-to-high (t_{PLH}) propagation delays when a single switching input causes one or more outputs to switch, $t_{sk(p)} = |t_{PHL} - t_{PLH}|$. Pulse skew is sometimes referred to as pulse width distortion or duty cycle skew.

Figure 1. Waveforms for Calculation of $t_{sk(o)}$ and $t_{sk(pp)}$

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
CDCLVD110VF	NRND	LQFP	VF	32	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CDCLVD110	
CDCLVD110VFG4	NRND	LQFP	VF	32	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CDCLVD110	
CDCLVD110VFR	NRND	LQFP	VF	32	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CDCLVD110	
CDCLVD110VFRG4	NRND	LQFP	VF	32	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CDCLVD110	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

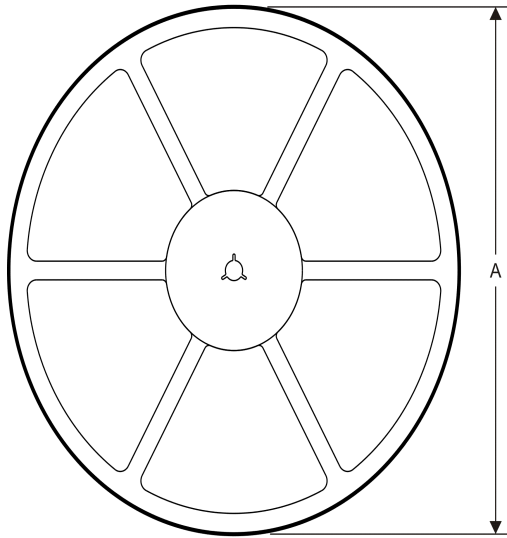
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDCLVD110VFR	LQFP	VF	32	1000	330.0	16.4	9.6	9.6	1.9	12.0	16.0	Q2

TAPE AND REEL BOX DIMENSIONS

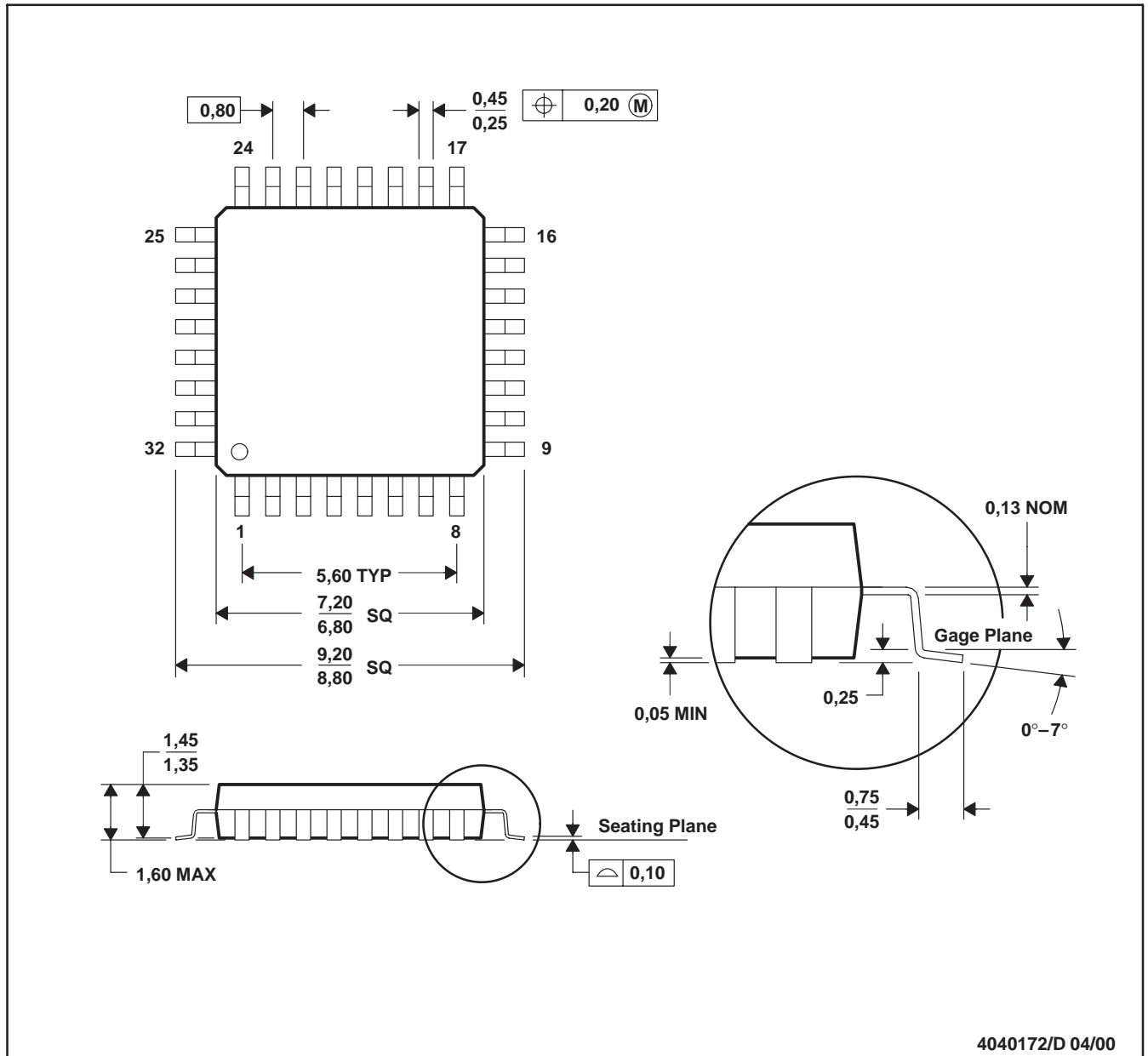


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDCLVD110VFR	LQFP	VF	32	1000	341.0	159.0	123.5

VF (S-PQFP-G32)

PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.

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